PCN# :P1B8A
Issue Date : Feb. 13, 2012

DESIGN/PROCESS CHANGE NOTIFICATION

This is to inform you that a change is being made to the products listed below.

Unless otherwise indicated in the details of this notification, the identified change will have no impact on product quality, reliability, electrical, visual or mechanical performance and affected products will remain fully compliant to all published specifications. Products incorporating this change may be shipped interchangeably with existing unchanged products.

This change is planned to take effect in 90 calendar days from the date of this notification. Please work with your local Fairchild Sales Representative to manage your inventory of unchanged product if your evaluation of this change will require more than 90 calendar days.

Please contact your local Customer Quality Engineer within 30 days of receipt of this notification if you require any additional data or samples. Alternatively, you may send an email request for data, samples or other information to PCNSupport@fairchildsemi.com.

Implementation of change:

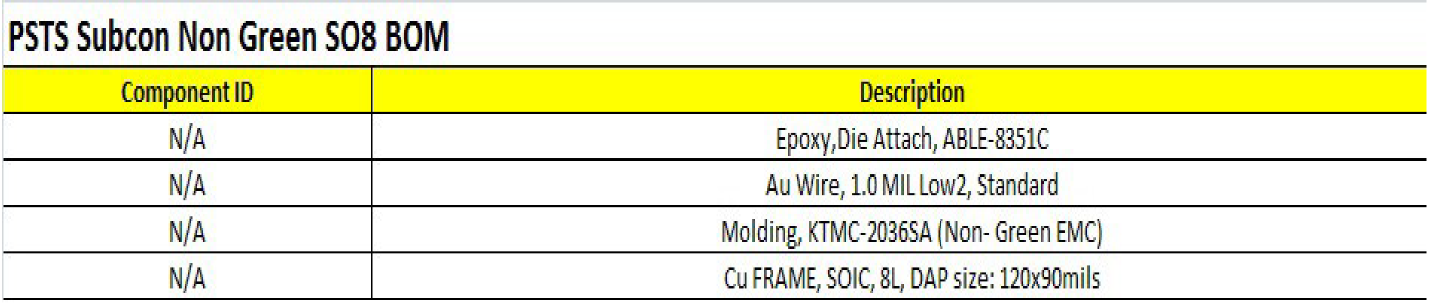
Expected First Shipment Date for Changed Product :May. 13, 2012

Expected First Date Code of Changed Product :1209

Last Date for Shipment of Unchanged Product :May. 13, 2012

Description of Change (From) :

Assembly and test from Subcon China PSTS for non low-Halogen, epoxy mold compound (EMC) devices

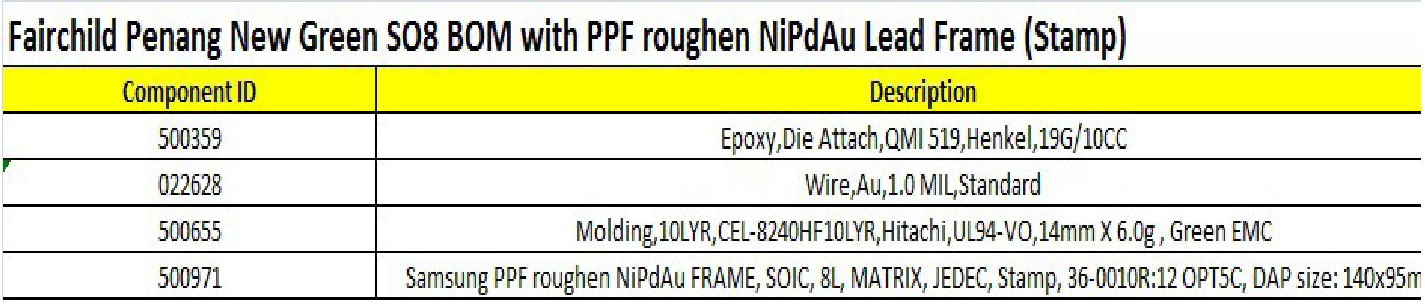


PSTS Subcon Non Green SO8 BOM

Component ID	Description
N/A	Epoxy,Die Attach, ABLE-8351C
N/A	Au Wire, 1.0 MIL Low2, Standard
N/A	Molding, KTMC-2036SA (Non- Green EMC)
N/A	Cu FRAME, SOIC, 8L, DAP size: 120x90mils

Description of Change (To) :

To Fairchild Semiconductor Penang Malaysia (FSPM) assembly and test site for low-Halogen EMC device



Fairchild Penang New Green SO8 BOM with PPF roughen NiPdAu Lead Frame (Stamp)

Component ID	Description
500359	Epoxy,Die Attach,QMI 519,Henkel,19G/10CC
022628	Wire,Au,1.0 MIL,Standard
500655	Molding,10LYR,CEL-8240HF10LYR,Hitachi,UL94-VO,14mm X 6.0g , Green EMC
500971	Samsung PPF roughen NiPdAu FRAME, SOIC, 8L, MATRIX, JEDEC, Stamp, 36-0010R:12 OPT5C, DAP size: 140x95m

Reason for Change:

This is the subcon simplification strategy in-sourcing project to phase out the subcon and improve Power Conversion High Voltage Integrated Circuit SOIC 8LD cost. Fairchild Penang will increase its test equipment utilization by in-sourcing all the active SOIC 8L package (refer to FSID device lists) assembled in PSTS using non low-Halogen EMC into FSPM with the change to low-Halogen EMC BOM set for production.

Affected Product(s):

FAN73611M	FAN73611MX	FAN7361MX
FAN7362MX	FAN73711M	FAN73711MX
FAN7371MX	FAN7380MX	FAN7380MX_WS
FAN7382MX	FAN7382MX_WS	FAN73832MX
FAN73833M	FAN73833MX	FAN7387M
FAN7387MX	FAN73901M	FAN73901MX
FAN7390M	FAN7390MX	FAN73932M
FAN73932MX	FAN7601BM	FAN7601BMX
FAN7711M	FAN7711MX	FAN7711SM
FAN7711SMX	FAN7711ZMX	FAN7842MX
KA34063ADTF	MC33063ADX	MC34063AD

Qualification Plan	**Device**	**Package**	**Process**	**No. of Lots**
Q20100651	FAN7390M	8SOIC	HDG4D	3

Test Description:	**Condition:**	**Standard :**	**Duration:**	**Results:**
MSL1 Precondition	260C, Wave soldering	**JESD22-A113**		0/144
C Scanning Acoustical Microscope	Delamination check			0/22
High Temperature Operating Life test	125C, 20V	**JESD22-A111**	1000hrs	0/77
High Temperature Reverse Biased Test	125C, 500V	**JESD22-A108**	1000hrs	0/77
High Temperature Storage Life Test	150C	**JESD22-A103**	1000hrs	0/77
Highly Accelerated Stress Test	130C, 85%RH, 10V	**JESD22-A110**	96hrs	0/45
Temperature Cycle	-65C, 150C	**JESD22-A104**	500cycles	0/77

Qualification Plan	**Device**	**Package**	**Process**	**No. of Lots**
Q20110304	FAN7371	SC70-6	FS35C	1

Test Description:	**Condition:**	**Standard :**	**Duration:**	**Results:**
MSL1 Precondition	260C, 3 cycles	**JESD22-A113**		0/276
Autoclave	121C, 100%RH	**JESD22-A102**	96 hrs	0/77
Highly Accelerated Stress Test	130C, 85%RH, 5.0V	**JESD22-A110**	96 hrs	0/45
High Temperature Storage Life	150C	**JESD22-A103**	1000 hrs	0/77
Static Operation Life	150C, 5.0V	**JESD22-A108**	1000 hrs	0/77
Temperature Cycle	-65C, 150C	**JESD22-A104**	500 cycles	0/77

Qualification Plan	**Device**	**Package**	**Process**	**No. of Lots**
Q20110305	FAN7711M	8SOIC	HDG4	1

Test Description:	**Condition:**	**Standard :**	**Duration:**	**Results:**
MSL1 Precondition	260C, Wave soldering	**JESD22-A113**		0/144
C Scanning Acoustical Microscope	Delamination check			0/22
High Temperature Operating Life test	125C, 14V	**JESD22-A111**	1000hrs	0/77
High Temperature Reverse Biased Test	125C, 500V	**JESD22-A108**	1000hrs	0/77
High Temperature Storage Life Test	150C	**JESD22-A103**	1000hrs	0/77
Highly Accelerated Stress Test	130C, 85%RH, 12V	**JESD22-A110**	96hrs	0/45
Temperature Cycle	-65C, 150C	**JESD22-A104**	500cycles	0/77